

L	MODIFY DIMENSION	Kevin	8/6/09'
K	MODIFY DIMENSION	Hanson	5/6/09'
J	REVISE NOTES 4	AXL	2/3/09'
I	ADD ORDER INFORMATION	Vegas	10/22/08
H	ADD 30% GF FOR HOUSING MATERIAL	Kevin	10/21/08
G	MODIFY DIMENSIONS & NOTES	Kevin	10/15/08
F	ADD NOTES AND SPECIFY MATTE TIN on Notes 2b.	AXL	10/6/08'
E	ADD DIM. ZONE A-3, B-2 AND B-3	AXL	9/24/08'
D	ADDED VIEWS	S.LAU	6/18/08
C	ADDED DIMENSION	S.LAU	6/12/08
B	ADD PCB LAYOUT	S.LAU	6/12/08
A	ISSUED	S.LAU	6/7/08'
REV	ECN NO.	NAME	DATE

TOLERANCE	
LINEAR	ANGLES
X. ± 0.30	X° ± 2.00°
.X ± 0.20	.X° ± 1.00°
.XX ± 0.10	.XX° ± 0.50°
.XXX ± 0.05	.XXX° ± 0.10°

GENESIS
TECHNOLOGY, INC. 1015 GRANT STREET S.E. ATLANTA, GA 30315
a Genesis Electro-Mechanical Company

APPD: _____ MAT'L: _____
CHKD: _____ FINISH: _____
DRWN: AXL Q'TY: _____

TITLE: SMART CARD CONNECTOR CLOSE TYPE	
PART NO. SMCR-2008-AKX0T1	
DWG NO. GTI08-30212	
UNITS: MM	SCALE: NONE
SHEET: 1 OF 2	REV: L

I ORDER INFORMATION

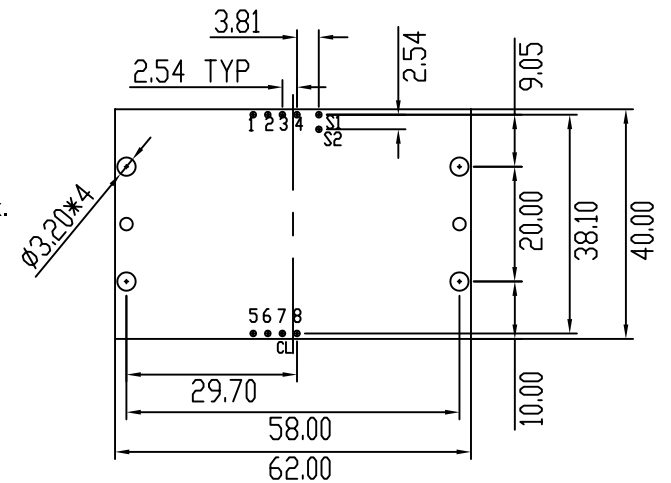
SMCR- 20 08 - A K X 0 T 1

① ② ③ ④ ⑤ ⑥ ⑦

- 1. CONNECTOR:
SMCR: SMART CARD R/A CONNECTOR
- 2. TYPE:
20: FEMALE, DIP, WITH CLOSE SWITCH, HEIGHT 3.3mm
- 3. POSITIONS
08: 8 POSITIONS
- 4. INSULATOR MATERIAL
A: PBT
- 5. INSULATOR COLOR
K: BLACK
- 6. CONTACT PLATING
1: GOLD FLASH
5: GOLD 15 u"
- 7. SHIELD PLATING
0: NONE SHIELD

Notes:

- F** 1. Electrical:
 - a. Voltage Rating: AC 35V / Pin.
 - b. Current Rating: 1 Ampere.
 - c. Insulation Resistance: 1000M ohms min.
 - d. Dielectric Withstand Voltage: AC 500V/1 min.
 - e. Contact Resistance: 40 m ohms max initial.
- 2. Mechanical:
 - a. Material:
 - Contacts: Phosphor Bronze.
 - H** **G** Housing/Flammability Rating: PBT+30% GF, UL94V-0.
Switch: Copper Alloy.
Ground spring pin / pin: copper alloy, thickness = 0.25 ± 0.02.
 - b. Plating:
 - G** Contacts: Nickel 50u" underplate and gold plated on contact area.
 - F** Matte Tin 100u" on solder area.
Ground spring pin / pin: Matte Tin or gold plate on all surface, nickel on all surface.
 - c. Durability: 100,000 Cycles.
 - d. Mating force: 1,500 g Max.
Unmating force: 150 g Min.
 - e. Coplanarity of SMT Leads: Not Applicable.
 - f. Solderability: More than 95% of solderable area shall be covered with solder after 5~10 seconds flux deep.
 - g. Soldering Profile: 255° C ± 3° C for 3 ± 0.3 seconds
- 3. Environmental:
 - a. Operating/Storage Temperature: -40° C to +80° C.
 - b. Heat Resistance: Per Mil-Std-1344A method 1005.1 connector 3 , Contact Resistance: 60 m ohms Max.
 - c. Cold Resistance: -40° C for 96hours, Contact Resistance: 60 m ohms Max.
 - d. Thermal Shock: Per Mil-Std-1344A method 1003.1 Condition A, Contact Resistance: 60 m ohms Max.
 - e. Steady State Humidity: Per Mil-Std-1344A method 1002.2 type 1 condition B, Contact Resistance: 60 m ohms Max.
 - f. Salt Spray: Per Mil-Std-1344A method 1001.1 test condition A, , Contact Resistance: 60 m ohms Max.
 - g. Vibration: Per Mil-Std-202F Method 214A test condition letter A, No discontinuity greater than 1 u second.
 - h. Mechanical Shock: Per Mil-Std-1344A Method 2004.1 condition D, No discontinuity greater than 1 u second.
- 4. Compliance:
 - J** a. Fully Compatible with ISO7816-2 cards.
 - b. RoHS 6/6 compliant.



L **B** COMPONENT SIDE

PART NO.	SMCR-2008-AKX0T1	SHEET	REVISION
DWG NO.	GTI08-30212	2 OF 2	SEE SHEET 1